4.1 Structure and bonding

Name: _____ Class: _____ Date: _____ **Total: 14 marks**

KEY WORDS crystal structure • atomic packing factor • grain refinement

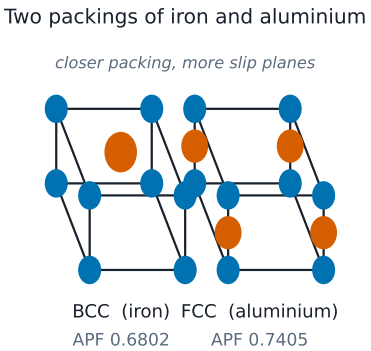
Objective

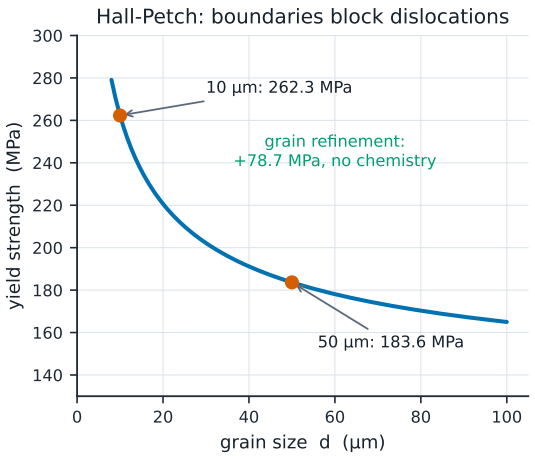
Connect crystal packing and grain structure to yield strength: packing factors, Hall-Petch arithmetic, and the grain size a specification demands.

1 Key knowledge and worked examples

■ Packing and blocking

APF: BCC $\pi\sqrt{3}/8 = 0.6802$, FCC $\pi/(3\sqrt{2}) = 0.7405$. Hall-Petch: $\sigma_y = \sigma_0 + k/\sqrt{d}$.





*Denser packing, finer grains

■ Worked example. The bracket steel

$\sigma_0 = 120$ MPa, $k = 0.45$: at 50 µm, $\sigma_y = 183.6$ MPa; at 10 µm, 262.3 MPa ✓ - a 78.7 MPa gain from processing alone.

2 Practice

A steel has $\sigma_0 = 100$ MPa and $k = 0.60$ MPa · √m.

2.1 The yield strength at grain sizes 25 µm and 16 µm (one decimal each). [4]

2.2 The largest grain size that meets a 300 MPa specification (micrometres, one decimal). [3]

2.3 The atomic packing factors of BCC and FCC (four decimals each), computed from the hard-sphere geometry. [4]

2.4 One sentence each: why does FCC deform more easily than BCC at room temperature, and why do grain boundaries strengthen a metal? [3]